

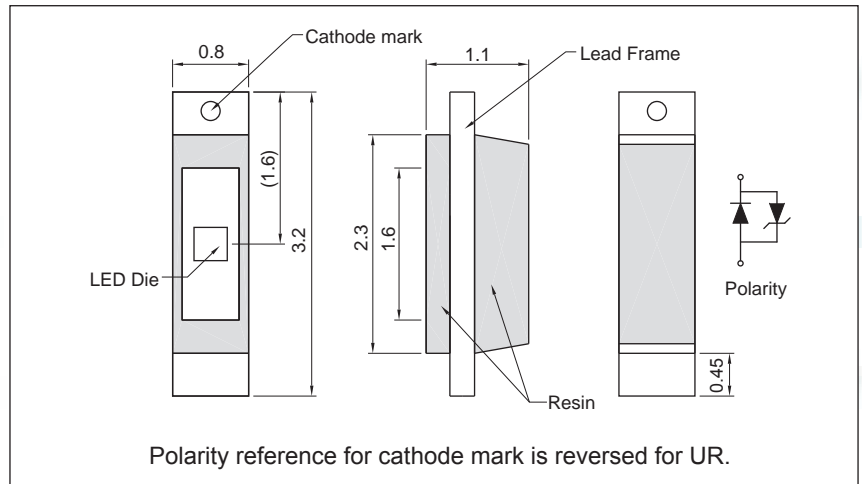
Features

- Chip LED (3.2x1.1x0.8)

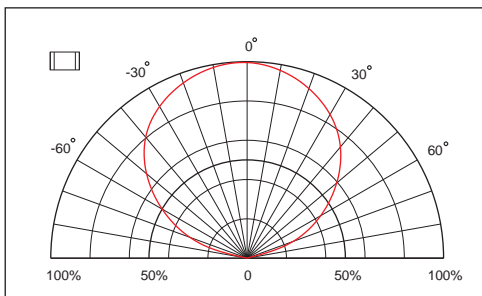
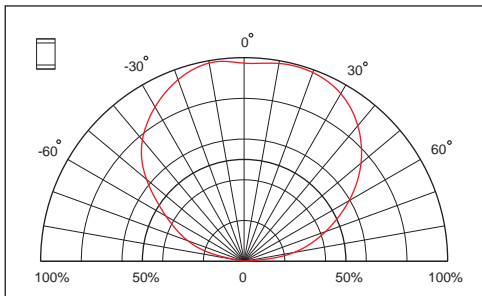


Package Outline Dimensions

(Unit: mm Tolerance:+/-0.1)

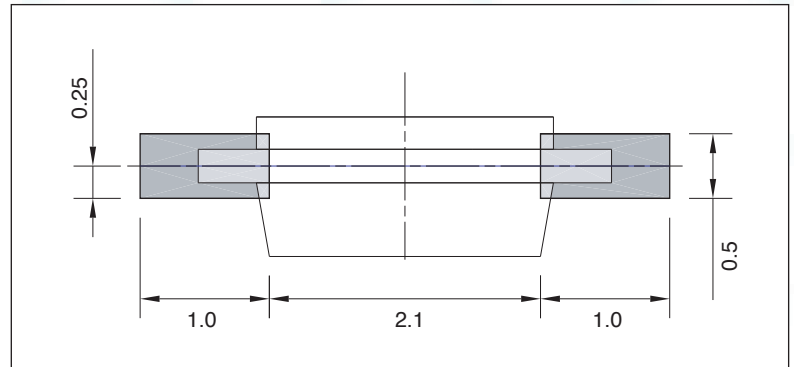


Directive Characteristics



Recommended Soldering Pattern

(Unit:mm)



Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	InGaN	Unit
Power Dissipation	P _D	117	mW
DC Forward Current	I _F	30	mA
Pulsed Forward Current	I _{FP} *	120	mA
Reverse Voltage	V _R	5	V
Operating Temperature	T _{OP}	-30 to 80	°C
Storage Temperature	T _{ST}	-40 to 85	°C

* 0.1msec pulse, 10% duty cycle.

Electrical / Optical Characteristics

(Ta=25°C)

Part Number	Emitting color	Material	Forward Voltage(V _F)		Wavelength (nm) typ.			Luminous Intensity (mcd)*		I _F (mA)	Viewing Angle 2θ _{1/2}
			typ.	max.	D	P	Δ	min.	typ.		
HT-V118NB	Blue	InGaN	3.3	3.9	470	468	40	80	180	20	120
HT-V118NG	Green	InGaN	3.3	3.9	527	520	40	150	300	20	120
HT-V118TW	White	InGaN	3.3	3.9	x=0.29 y=0.32	-	-	1000	1200	20	120

*Per NIST standards

